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 HITACHI CHEMICAL KK *J6 0068-935-A
 26.09.83-JP-177652 (19.04.85) B32b-07/12
 Adhesive coated insulating plate - having thermosetting layer
 consisting of acrylonitrile butadiene rubber phenol and epoxy
 resins ethylene acetic acid vinyl copolymer

C85-057273

Thermosetting adhesive layer consisting of acrylonitrile butadiene rubber, phenol resin, epoxy resin and ethylene acetic acid vinyl copolymer is formed on the surface of plate. Adhesive is an adhesive made up by uniformly mixing 25-80 wt. pt. acrylonitrile butadiene rubber, 10-55 wt. pt. phenol resin, 2-45 wt. pt. epoxy resin and 0.5-15 wt.pt. ethylene acetic acid vinyl copolymer with organic solvent. Or it is made by uniformly mixing 30-50 wt.pt. acrylonitrile butadiene rubber, 15-45 wt.pt. alkylphenol, 5-24 wt. pt. epoxy resin, 1-16 wt. pt. ethylene acid vinyl copolymer and 10-45 wt. pt. inorganic filler with organic solvent.

USE/ADVANTAGE - Provides plate used for mfg. a printed wiring plate forming a metal conductor circuit by means of electroless plating (5pp Dwg.No.0/0)

A(4-B4, 4-G7, 5-A1E1, 5-A1E2, 5-C1, 7-A4A, 7-A4B, 12-A5A, 4 2
 12-A5B, 12-A5C, 12-E7A) G(3-B2B, 3-B2D2, 3-B2D3, 3-B2E1,
 3-B2E2)

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